

IN THE CLAIMS:

Claims 5 and 6 have been amended herein. Please note that all claims currently pending and under consideration in the referenced application are shown below. Please enter these claims as amended. Please cancel claims 1 through 4, without prejudice to the filing of one or more divisional applications to the subject matter thereof. This listing of claims will replace all prior versions and listings of claims in the application.

Listing of Claims:

1-4. (Cancelled)

5. (Currently Amended) A method of processing electronic component assemblies, comprising:
~~securing~~ disposing a plurality of electronic component assemblies ~~in fixed positions secured to a~~
platen assembly in fixed positions with one side of each of the plurality of electronic
component assemblies including electronic components exposed through the platen
assembly;
securing the platen assembly to a platform within a stereolithography apparatus with the exposed
electronic components on the one side of each of the plurality of electronic component
assemblies facing upward;
forming at least one stereolithographic structure adjacent each of the exposed electronic
components on the one side of each of the plurality of electronic component assemblies;
and
removing the platen assembly from the stereolithography apparatus.

6. (Currently Amended) The method of claim 5, wherein ~~securing~~ disposing a
plurality of electronic component assemblies ~~in fixed positions secured to the platen assembly in~~
fixed positions with one side of each of the plurality of electronic component assemblies
including electronic components exposed through the platen assembly further comprises

~~securing~~~~disposing~~ the plurality of electronic component assemblies ~~in fixed positions secured~~ to the platen assembly with another, opposing side of each of the plurality of electronic component assemblies including electronic components exposed through the platen assembly.

7. (Previously Presented) The method of claim 6, further including:
after forming at least one stereolithographic structure adjacent each of the exposed electronic components on the one side of each of the plurality of electronic component assemblies, inverting the platen assembly;
securing the inverted platen assembly to a platform within a stereolithography apparatus with the exposed electronic components on the another, opposing side of each of the plurality of electronic component assemblies facing upward; and
forming at least one stereolithographic structure adjacent each of the exposed electronic components on the another, opposing side of each of the plurality of electronic component assemblies.

8. (Original) The method of claim 7, wherein inverting the platen assembly is effected prior to removal thereof from the stereolithography apparatus.

9. (Previously Presented) The method of claim 7, wherein inverting the platen assembly is effected after the removal thereof from the stereolithography apparatus and securing the platen assembly to the platform within the stereolithography apparatus with the exposed electronic components on the another, opposing side of each of the plurality of electronic component assemblies facing upward comprises securing the platen assembly to a platform within a second stereolithography apparatus.

10. (Previously Presented) The method of claim 7, wherein inverting the platen assembly is effected after the removal thereof from the stereolithography apparatus and securing the platen assembly to the platform within the stereolithography apparatus with the exposed electronic components on the another, opposing side of each of the plurality of electronic

component assemblies facing upward comprises securing the platen assembly to the platform within the same stereolithography apparatus.

11. (Previously Presented) A method of processing electronic components, comprising:
adhering a plurality of electronic components in fixed positions to one side of a film supported by a frame member;
securing the frame member to a platform within a stereolithography apparatus with the plurality of electronic components adhered to the one side of the film facing upward;
forming at least one stereolithographic structure adjacent each of the plurality of electronic components adhered to the one side of the film; and
removing the frame member from the stereolithography apparatus.

12. (Original) The method of claim 11, further comprising, after removing the frame member from the stereolithography apparatus, inverting the frame member and releasing the plurality of electronic components from the film.

13. (Original) The method of claim 12, wherein releasing the plurality of electronic components from the film comprises exposing the film to ultraviolet radiation from a side thereof opposite the one side to which the plurality of electronic components is adhered.

14. (Original) The method of claim 12, wherein releasing the plurality of electronic components from the film comprises releasing the plurality of electronic components into a tray divided into cells, each electronic component being released into a single cell.

15. (Previously Presented) The method of claim 14, further comprising forming the at least one stereolithographic structure adjacent each of the plurality of electronic components while the plurality of electronic components are located in the cells of the tray.

16. (Previously Presented) The method of claim 14, further comprising placing structures to effect external electrical communication on each of the plurality of electronic components while the plurality of electronic components are located in the cells of the tray.

17. (Original) The method of claim 12, wherein releasing the plurality of electronic components from the film comprises adhering the plurality of electronic components to another film.

18. (Previously Presented) The method of claim 17, further comprising forming the at least one stereolithographic structure adjacent each of the plurality of electronic components while the plurality of electronic components are adhered to the another film.

19. (Previously Presented) The method of claim 17, further comprising placing structures to effect external electrical communication on each of the plurality of electronic components while the plurality of electronic components are adhered to the another film.